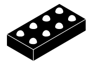
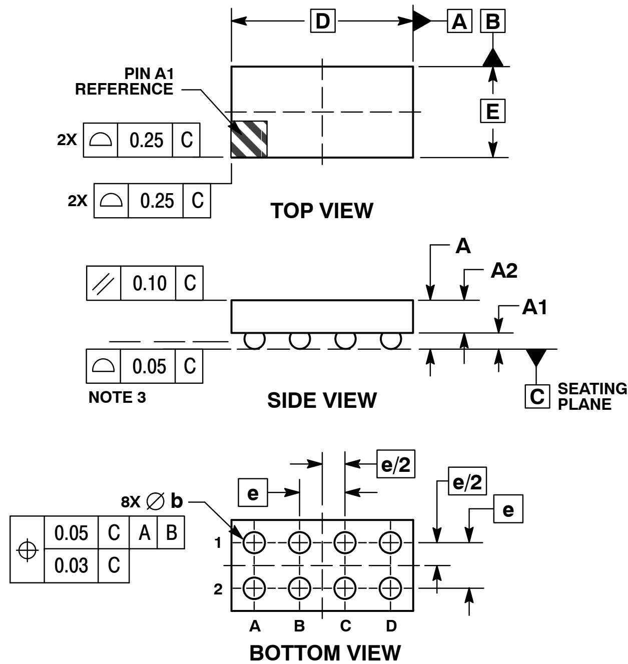


SCALE 4:1

WLCSP8, 2.0x1.0
CASE 567HD
ISSUE O

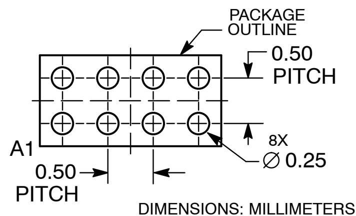
DATE 26 APR 2013



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS MIN	MILLIMETERS MAX
A	---	0.66
A1	0.21	0.27
A2	0.36 REF	
b	0.29	0.34
D	2.00 BSC	
E	1.00 BSC	
e	0.50 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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